



Material Content Data Sheet



Sales Product Name				IPS040N03L G		Issued		25. September 2017	
MA#				MA000820162					
Package				PG-TO251-3-311		Weight*		334.83 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.734	0.52	0.52	5180	5180	
leadframe	inorganic material	phosphorus	7723-14-0	0.047	0.01		139		
	non noble metal	iron	7439-89-6	0.156	0.05		465		
	non noble metal	copper	7440-50-8	155.372	46.40	46.46	464035	464639	
	non noble metal	aluminium	7429-90-5	3.594	1.07	1.07	10735	10735	
wire	non noble metal	aluminium	7429-90-5	3.594	1.07	1.07	10735	10735	
encapsulation	organic material	carbon black	1333-86-4	0.323	0.10		965		
	plastics	epoxy resin	-	19.513	5.83		58277		
	inorganic material	silicondioxide	60676-86-0	127.099	37.96	43.89	379593	438835	
leadfinish	non noble metal	tin	7440-31-5	3.002	0.90	0.90	8964	8964	
plating	inorganic material	phosphorus	7723-14-0	0.004	0.00		11		
	non noble metal	nickel	7440-02-0	1.555	0.46	0.46	4643	4654	
solder	non noble metal	tin	7440-31-5	0.036	0.01		107		
	noble metal	silver	7440-22-4	0.045	0.01		133		
	non noble metal	lead	7439-92-1	1.707	0.51	0.53	5097	5337	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		19		
	non noble metal	iron	7439-89-6	0.021	0.01		62		
	non noble metal	copper	7440-50-8	20.617	6.16	6.17	61575	61656	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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